

# ALICE 3 RICH: cooling and mechanics

ALICE Upgrade Week  
7th-11th October, 2024

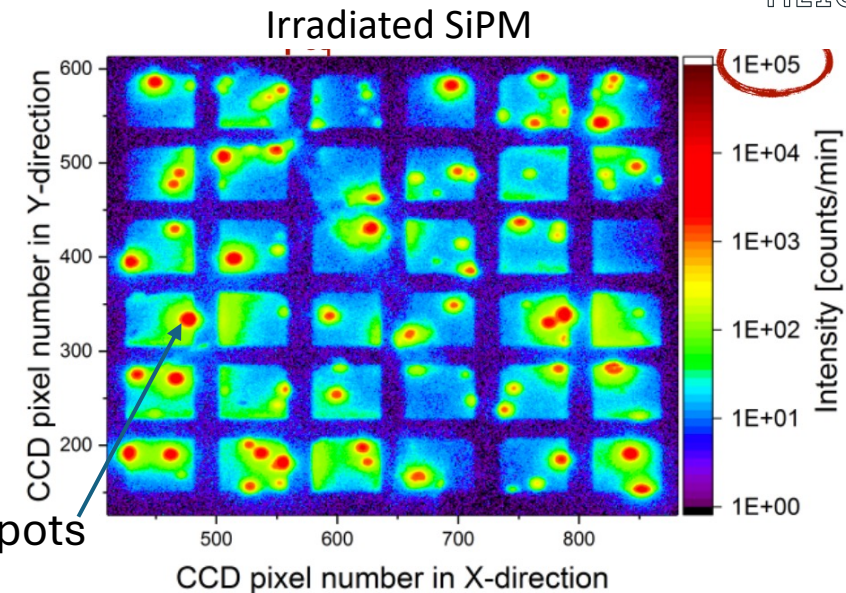
Eugenio Nappi (INFN, Bari), Giacomo Volpe (University & INFN, Bari)

# The barrel RICH challenges – Radiation Load

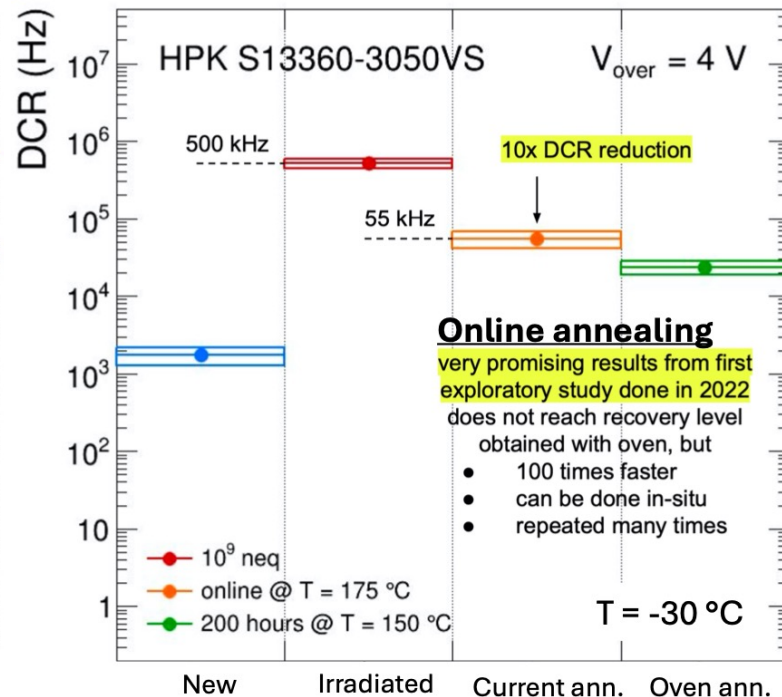
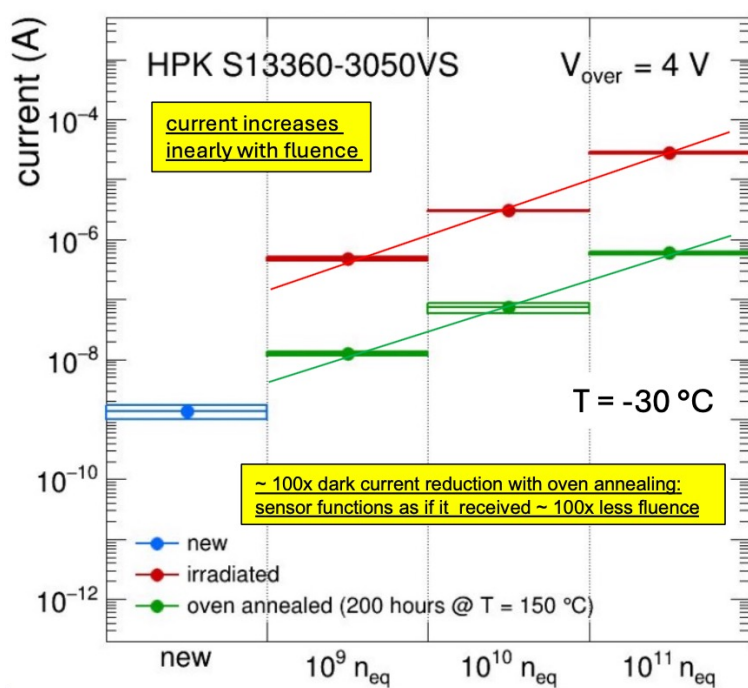


- High radiation load expected in the barrel ( $\text{NIEL} \sim 8.4 \times 10^{11} \text{ 1 MeV neq/cm}^2$ )  $\rightarrow$  SiPM DCR increases to not tolerable values ( $> 1 \text{ MHz/mm}^2$ )

- Improve SiPM radiation hardness
- Development of cooling/annealing strategy!**

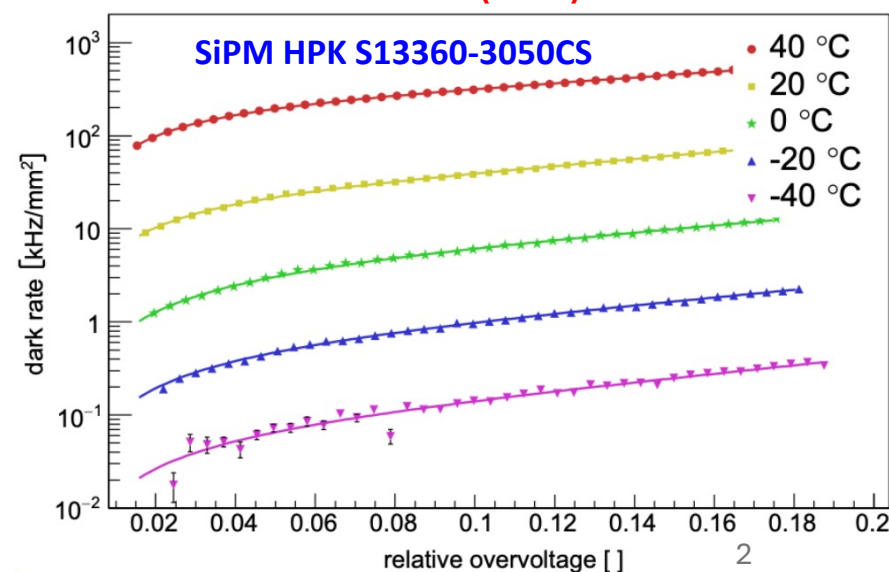


From R. Preghenella



Hot spots

NIMA 846 (2017) 106–125



# SiPMs cooling concept

## Dual-phase CO<sub>2</sub> cooling - A good choice for HEP applications

- advantages of dual-phase CO<sub>2</sub> cooling for HEP applications:
  - **large latent heat transfer** due to the phase change energy for the transition of liquid to gas
  - operation with **low mass flow** of the coolant is possible
  - **low mass flow as well as a low liquid viscosity results in a low pressure drop along cooling pipe**
    - a low pressure drop allows the use of small pipe diameters or technical solutions like micro-channel cooling, which allows new detector design concepts
  - high **heat transfer capability** (typical ~8000 W/Km) is possible despite small pipe diameters
  - practical **temperature range** of -40°C to 25°C for detector application
  - CO<sub>2</sub> is a **natural**, non-toxic, non-flammable, radiation resistant and non-magnetic gas

## Micro-channel cooling on Si - A silicon-embedded Technologies

- micro-channel cooling in Si is a favourable technology
  - **optimized thermal contact with heat sources**
  - heavily simplified assemblies
  - reduction of material
  - **efficient for cooling “chip-like” heat densities**
- basic technological process: deep RIE + (anodic, eutectic, fusion) wafer bonding
- further integrations also possible!
  - example: metal Re-Distribution Layers (RDL) (*M. Ullán et al. (HSTD13, 2023)*)



Hybrid pixel detector & micro-channel cooling plate



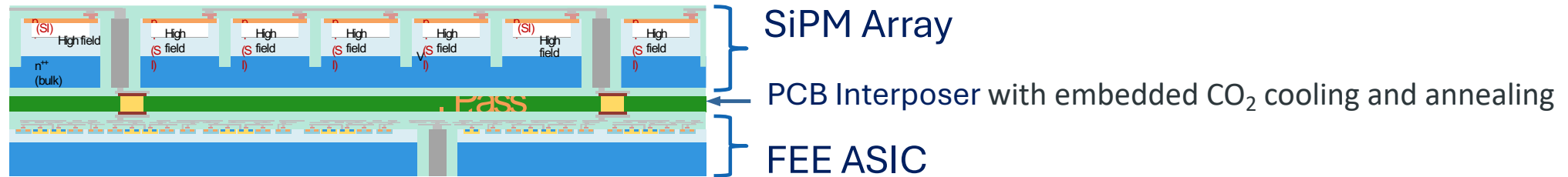
Monolithic CMOS detector



Monolithic CMOS detector with integrated micro-channels

# SiPMs cooling concept

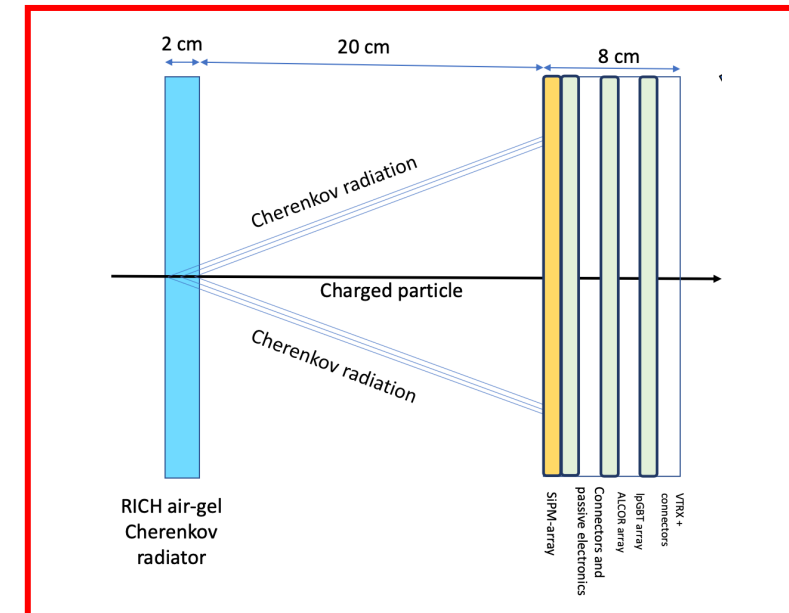
- Cool down the sensor to  $-40\text{ }^{\circ}\text{C}$ 
  - Dual-phase  $\text{CO}_2$  micro-channels through a special interposer (between the sensor and the FEE ASIC)



- Isolate the detector from the external environment
  - Thermal insulator vessel:  $-40\text{ }^{\circ}\text{C}$  inside,  $20\text{ }^{\circ}\text{C}$  outside

***Involvement of  
Politecnico of Bari!***

## Thermal shield



## Cylindrical projective geometry

- All aerogel tiles oriented toward nominal interaction point
- Full coverage to charged particles without overlaps
- Trapezoidal tile profile to maximize the acceptance

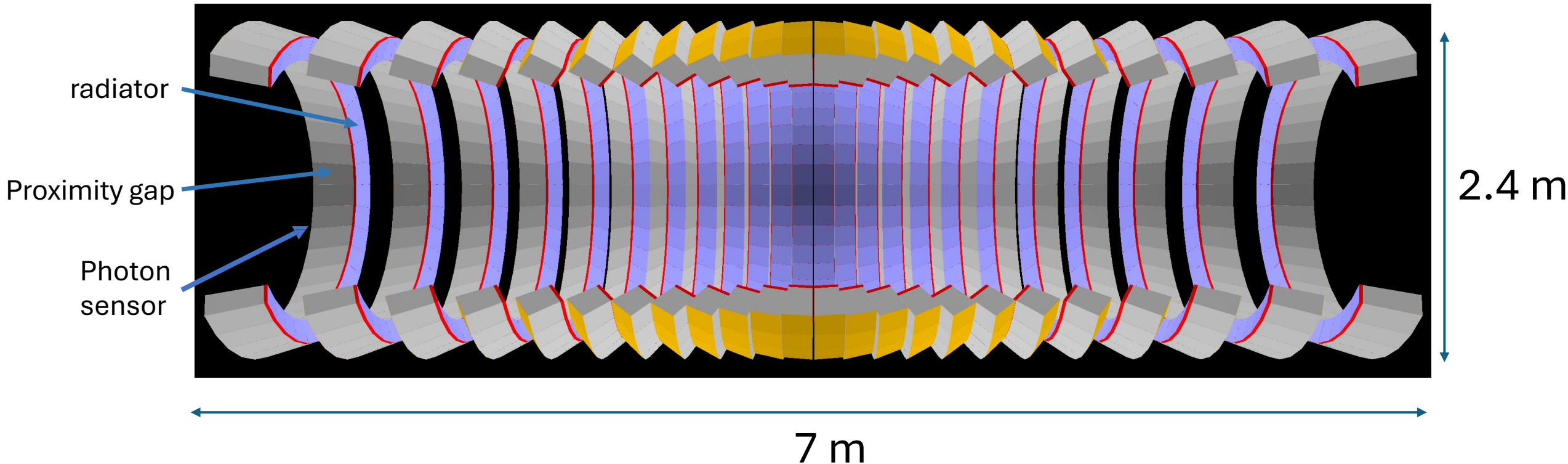


24 sectors in  $z$

36 modules in  $r\phi$  for each sector

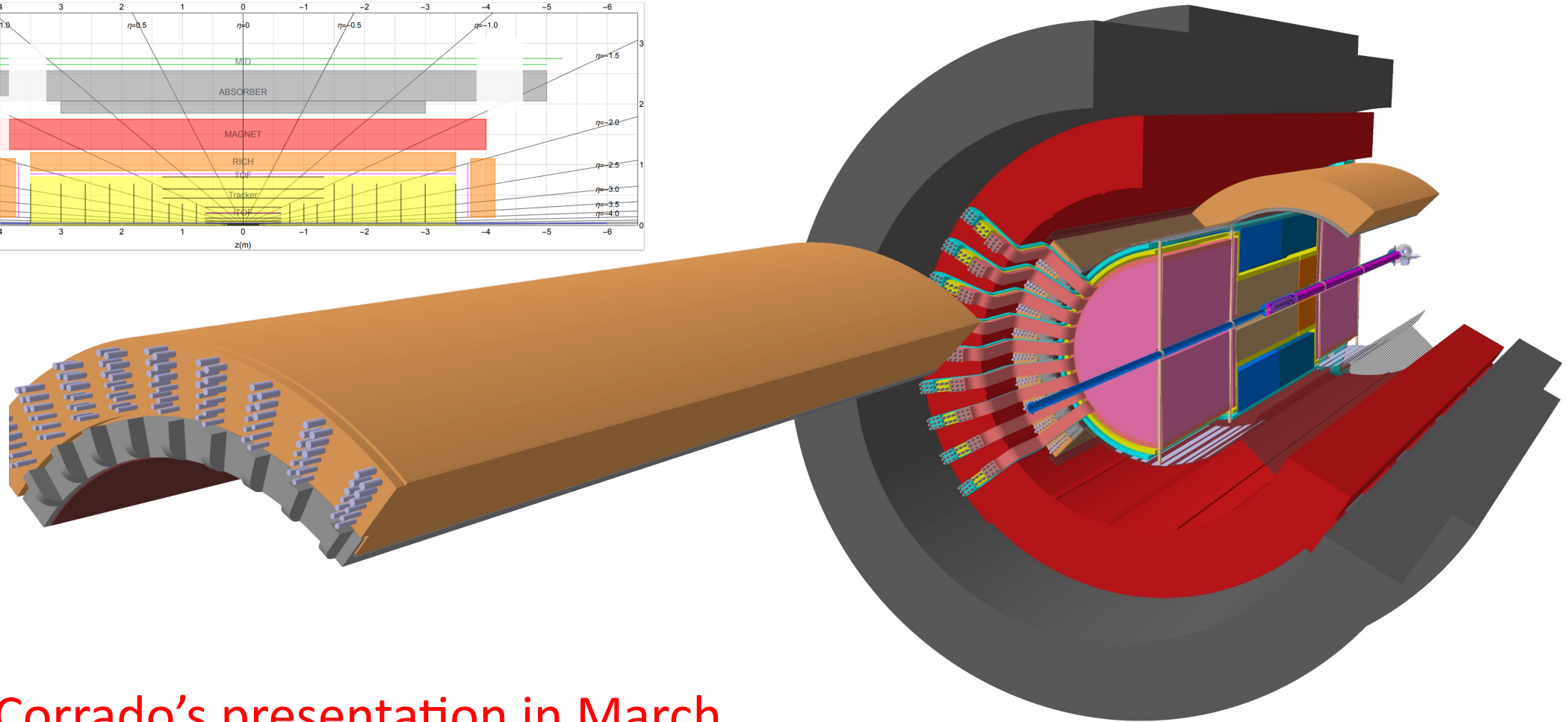
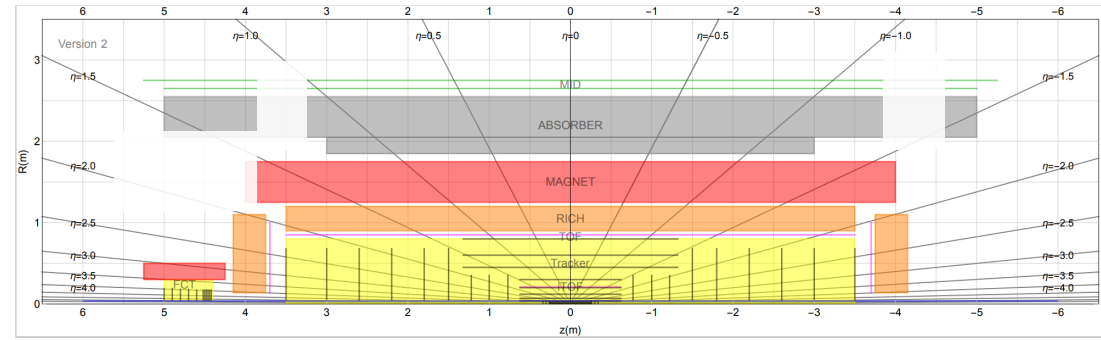
Sensor area  $\cong 30.7 \text{ m}^2$

# channels  $\cong 7 \cdot 10^6$



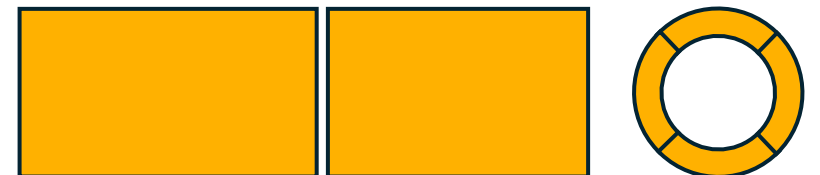


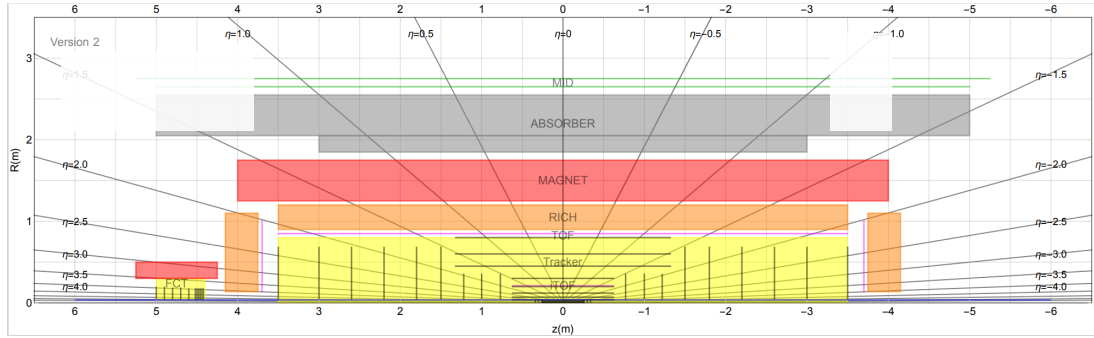
# Mechanics



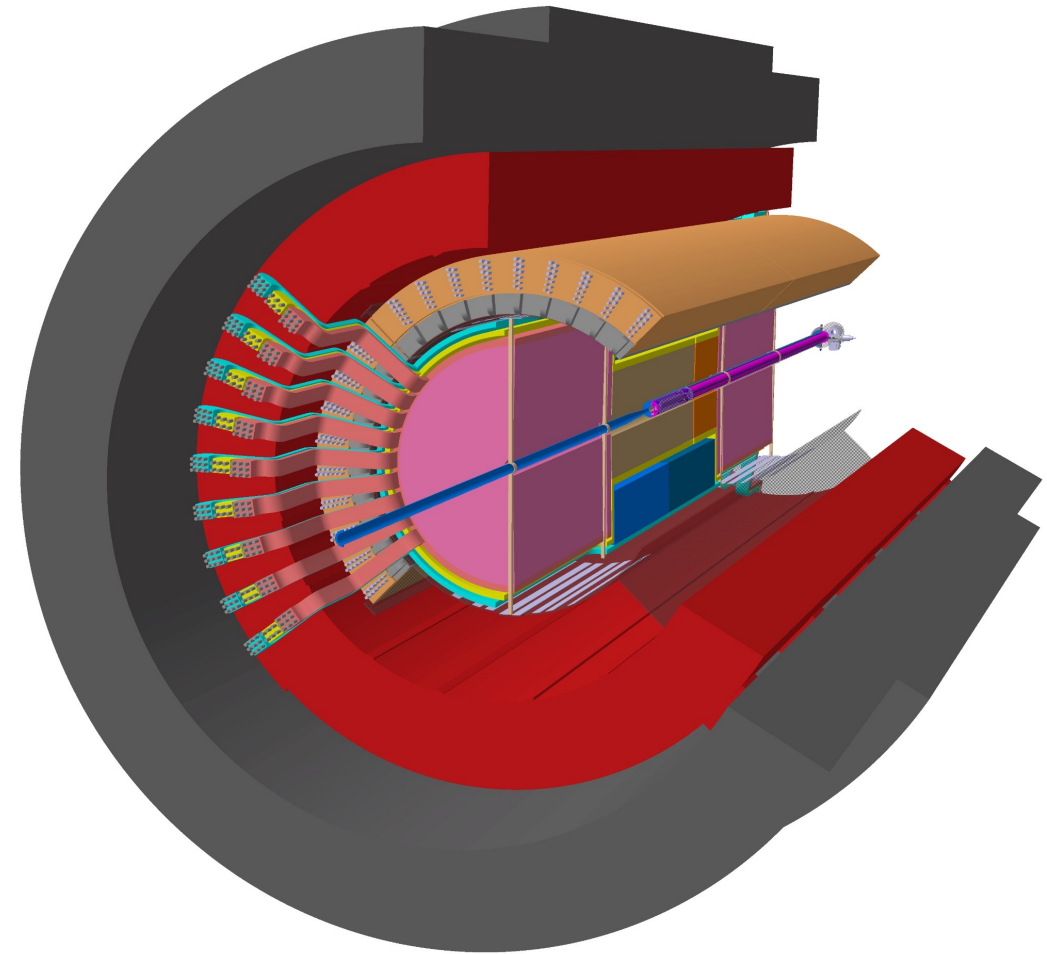
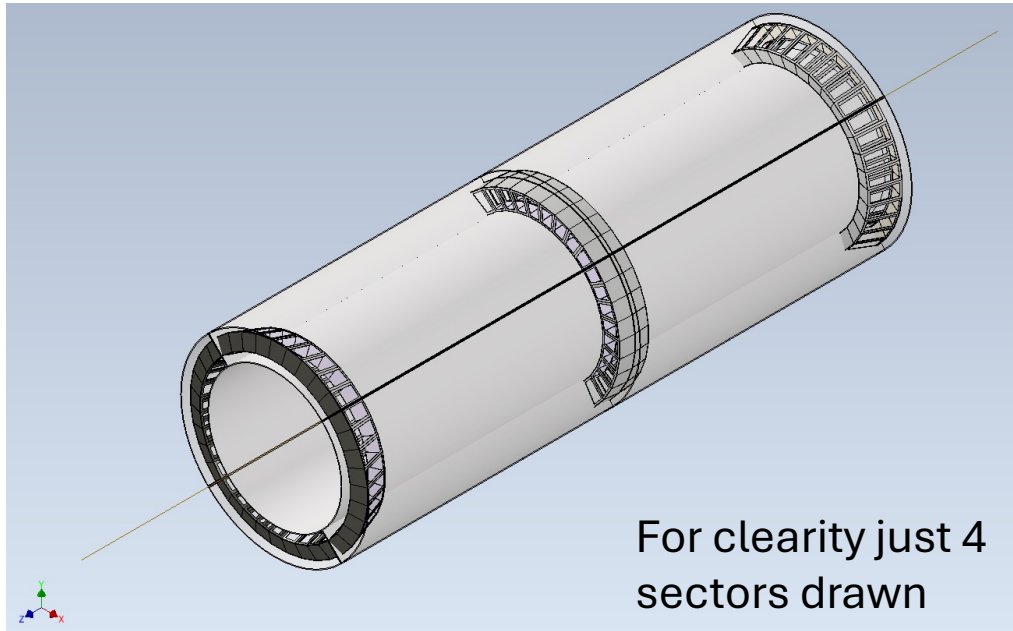
From Corrado's presentation in March

TOF+RICH (1/4) insertion from A-side



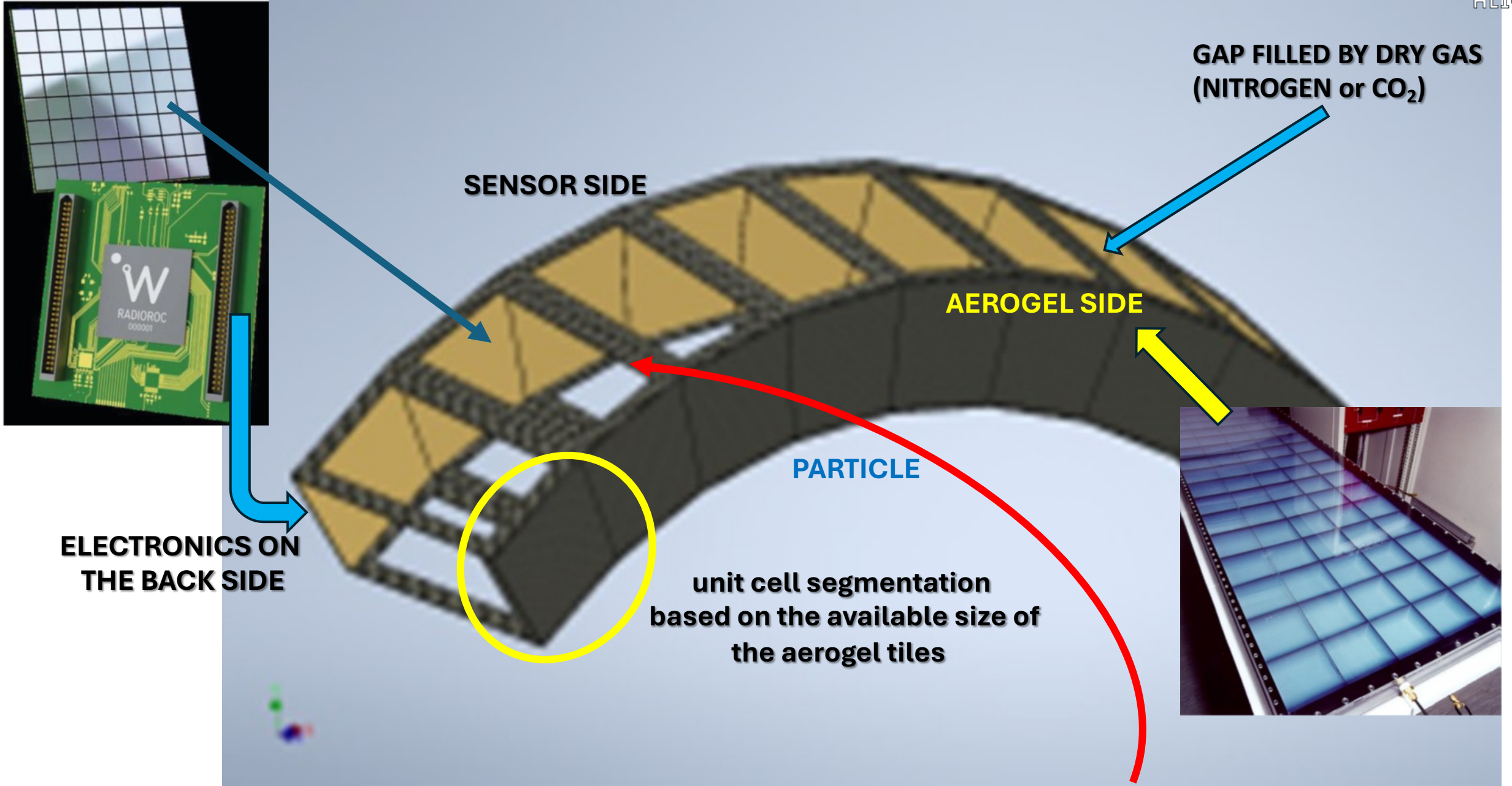


Full cylinder divided in 8 modules



TOF+RICH (1/4) insertion from A-side

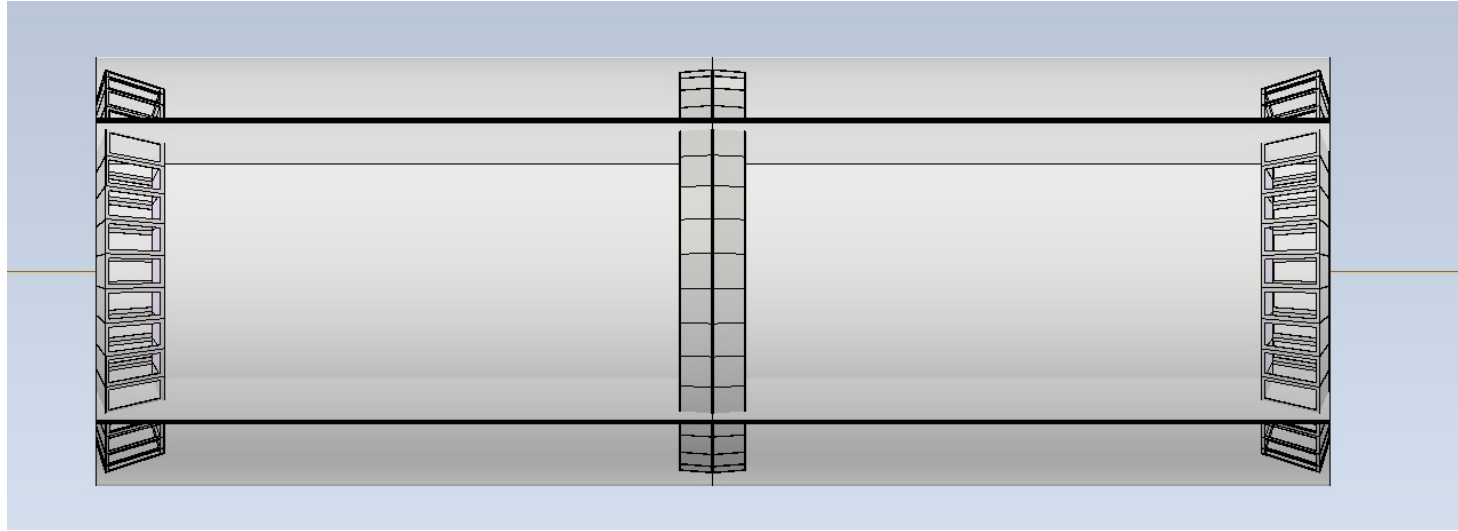
# Mechanics



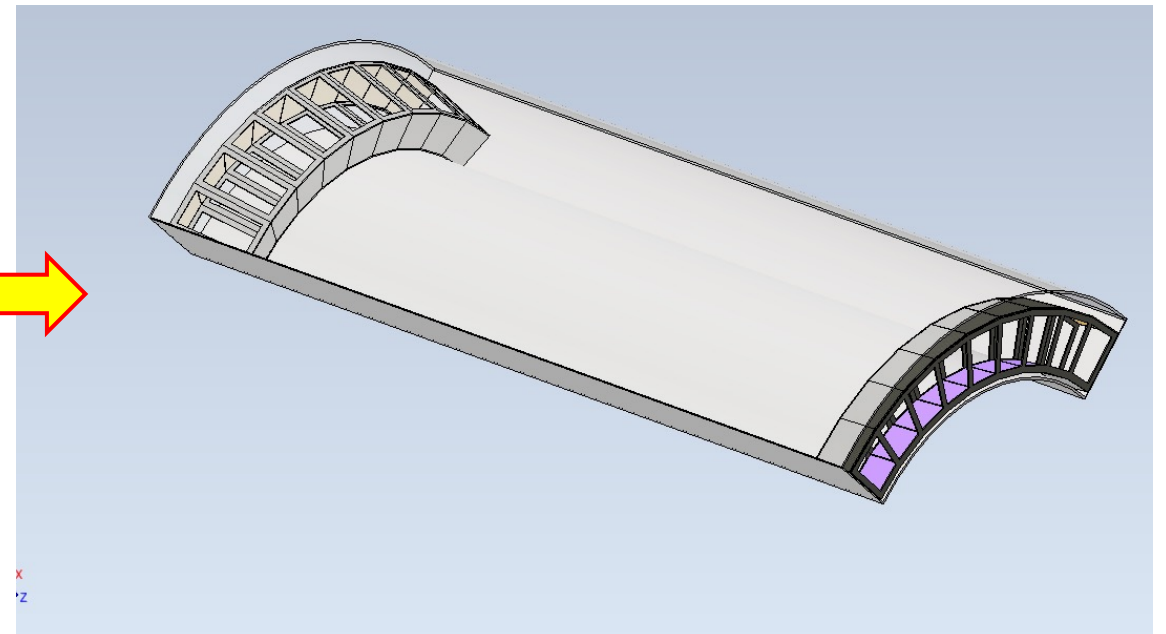
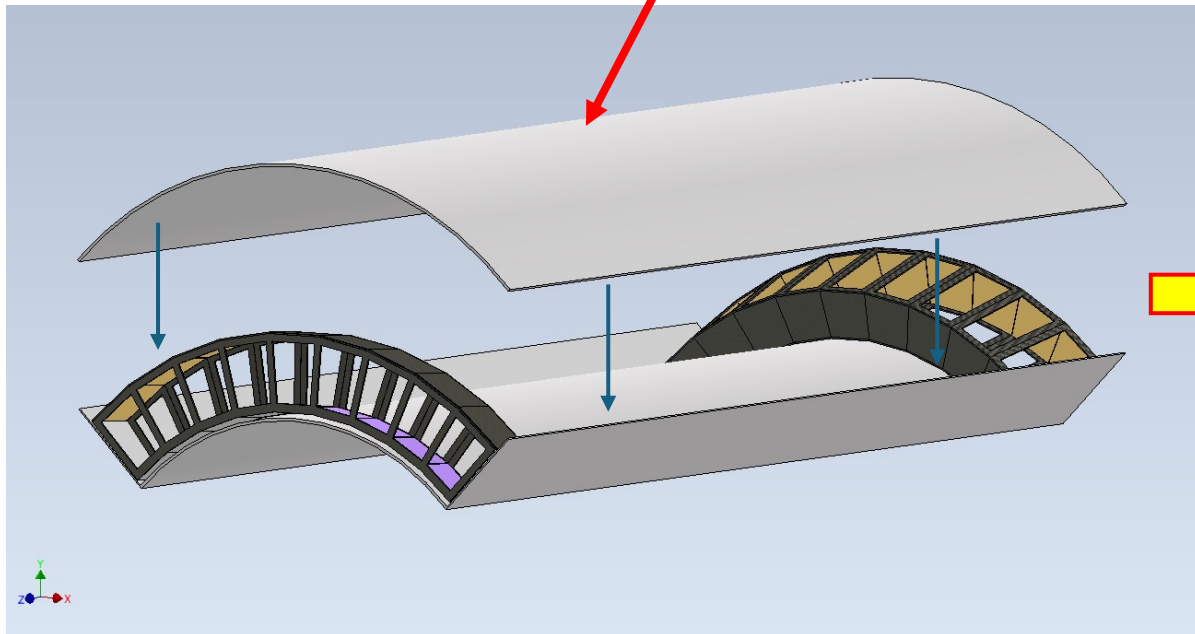
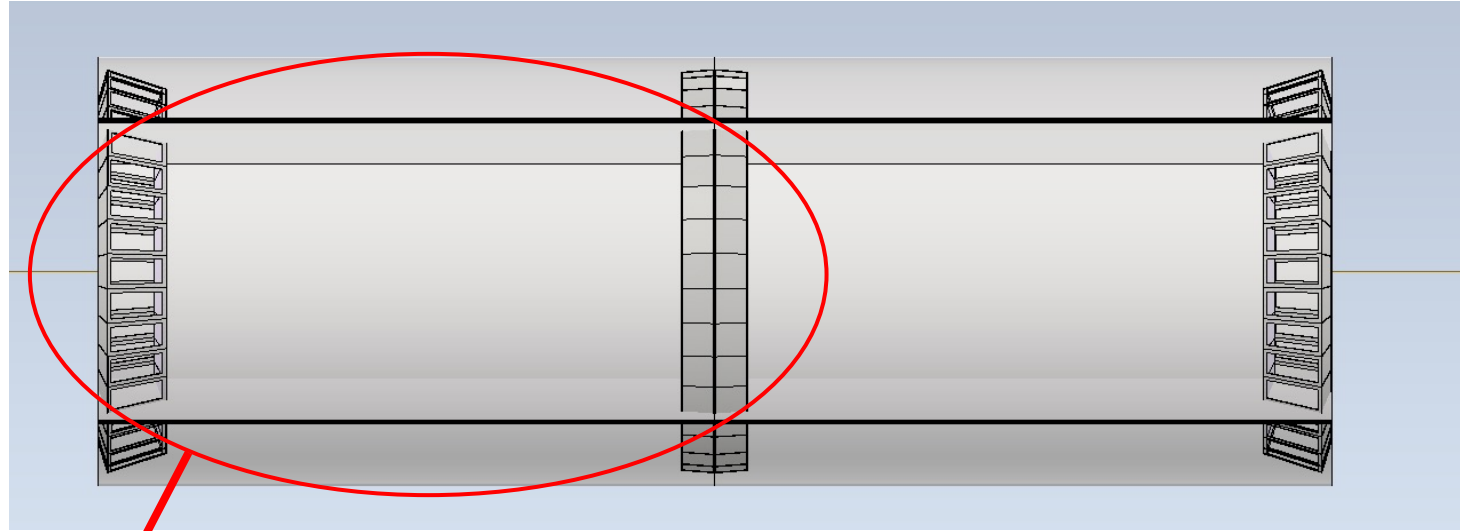


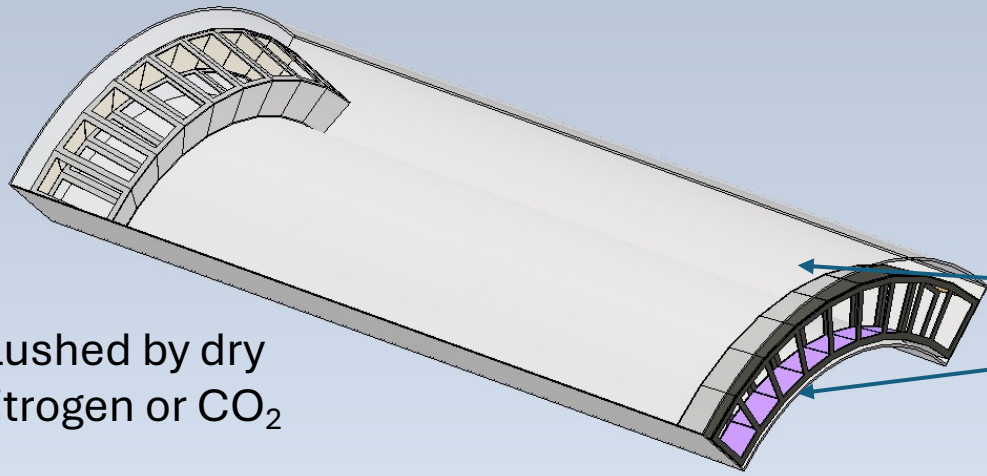
# Mechanics

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# Mechanics

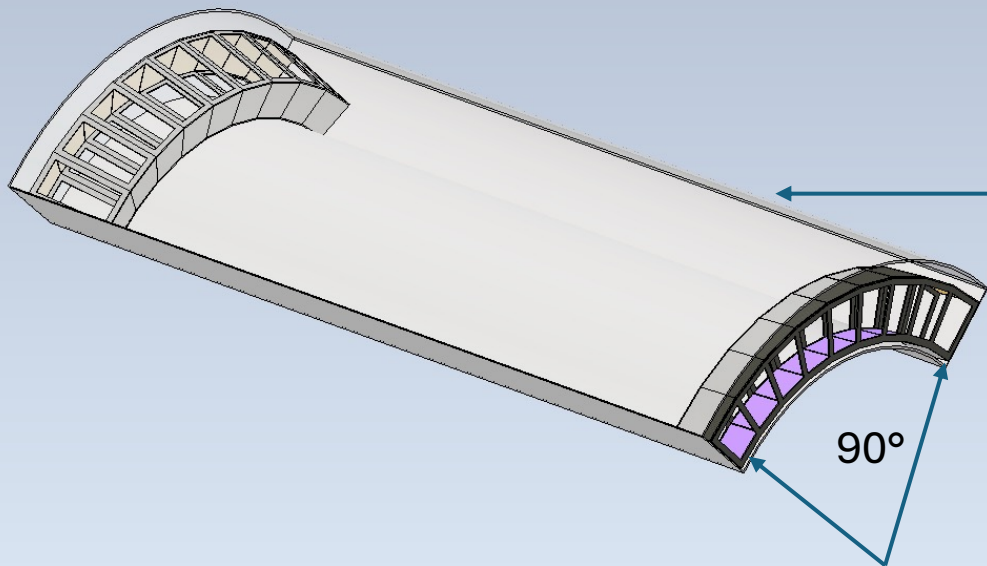




THERMAL SHIELD (due to space constraints no more than few centimeters of thickness)

Inner temperature = - 40 ° C

Outer temperature = 20 ° C



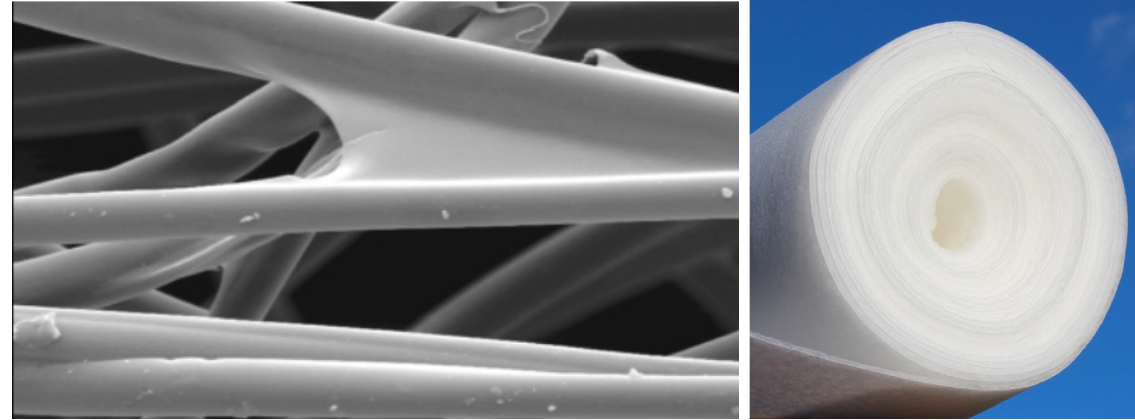
Full cylinder divided in 2 cylinders, each of them divided in 4 slices (90° each)

# Thermal shield

## ***Aerogel as thermal insulator!!***

### ***Thermal Wrap Aerogel Blankets (CABOT)***

Made of aerogel granules embedded in non-woven fibers, which produces a flexible, compressible, and highly efficient insulation material.



### ***Flexible aerogel blanket (Cryogel® Z )***

Composed of a flexible aerogel blanket laminated to a vapor retarder.





## Conclusion & outlook

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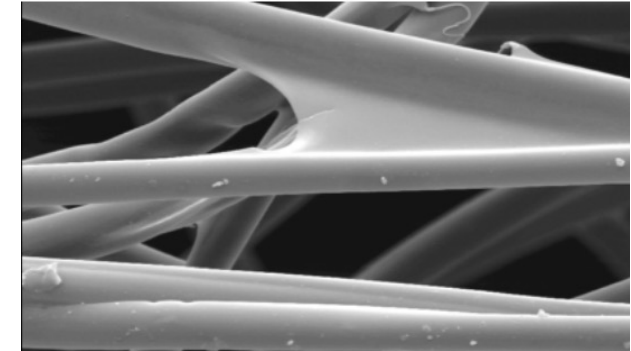
- Cooling the SiPM sensors is crucial for reducing the dark count rate (DCR) to acceptable levels for single-photon detection.
- We have begun exploring the possibility of using dual-phase CO<sub>2</sub> micro-channels within the interposer.
- Dedicated studies on the interposer will commence soon.
- A thermal shield will be required to isolate the detector from external environmental factors.
  - Specific heat exchange simulations will be carried out to determine the materials and thickness needed.
- Initial CAD drawings of the detector structure have been completed.

# Backup

## *Aerogel as thermal insulator!!*

### *Thermal Wrap Aerogel Blankets (CABOT)*

Made of aerogel granules embedded in non-woven fibers, which produces a flexible, compressible, and highly efficient insulation material.



### **Thermal Wrap™ blanket - Thermal conductivity with temperature**

| Mean Temp °C | Thermal Conductivity (mW/mK) | Mean Temp °F | Thermal Conductivity (BTU/hr*ft*°F) |
|--------------|------------------------------|--------------|-------------------------------------|
| -129         | 13                           | -200         | 0.0075                              |
| -73.3        | 17                           | -100         | 0.0098                              |
| -17.8        | 20                           | 0            | 0.0116                              |
| 23.9         | 23                           | 75           | 0.0133                              |
| 37.8         | 25                           | 100          | 0.0144                              |
| 93.3         | 32                           | 200          | 0.0185                              |



## *Aerogel as thermal insulator!!*

### *Flexible aerogel blanket (Cryogel® Z)*

Composed of a flexible aerogel blanket laminated to a vapor retarder.



### THERMAL CONDUCTIVITY †

Tested in accordance with ASTM C177

| Mean Temp.<br>°F / °C | <i>k</i><br>BTU-in/hr-ft <sup>2</sup> -°F / mW/m-K |
|-----------------------|--|
| -200 / -129           | 0.096 / 14   |
| -100 / -73.3          | 0.10 / 15  |
| 0 / -17.8             | 0.11 / 16  |
| 75 / 23.9             | 0.12 / 17  |
| 100 / 37.8            | 0.12 / 17  |
| 200 / 93.3            | 0.13 / 19  |

†Thermal conductivity measured at a compressive load of 2 psi.

